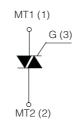
RoHS



STANDARD TRIAC

TO-263AB / D2PAK





On-State Current

Gate Trigger Current

12 Amp

 \leq 100 mA

Off-State Voltage

200 V ÷ 800 V

FEATURES

- Glass/passivated die junctions
- Medium current Triac
- Ideal for automated placement
- Low thermal resistance
- High surge current capability
- Low forward voltage drop
- Solder dip 260°C, 10s
- 30idel dip 200 C, 103
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC
- Meets MSL level 3, per J-STD-020, LF maximum peak of 260° C

MECHANICAL DATA

- Case: TO-263AB / D2PAK. Epoxy meets UL 94V-0 flammability rating.
- Polarity: As marked on the body.
- **Terminals:** Matte tin plated leads, solderable per MIL-STD-750 Method 2026, J-STD-002 and JESD22-B102. Consumer grade, meets JESD 201 class 1A whisker test.

TYPICAL APPLICATIONS

Suitable for general purpose AC switching. They can be used as an ON/OFF function in applications such as static relays, heating regulation, induction motor starting circuits... or for phase control operation in light dimmers, motor speed controllers,

Maximun Ratings and Electrical Characteristics at 25°C

SYMBOL	PARAMETER	CONDITIONS	Value	Unit
I _{T(RMS)}	RMS On-state Current (full sine wave)	All Conduction Angle, T _c = 105 °C	12	А
I _{TSM}	Non-repetitive On-State Current	Full Cycle, 60 Hz (t = 16.7 ms)	109	А
I _{TSM}	Non-repetitive On-State Current	Full Cycle, 50 Hz (t = 20 ms)	100	А
I ² t	Fusing Current	tp = 10 ms, Half Cycle	78	A ² s
I _{GM}	Peak Gate Current	20 μs max. Tj = 125 °C	4	А
P _{G(AV)}	Average Gate Power Dissipation	Tj = 125 °C	1	W
dI/dt	Critical rate of rise of on-state current	$I_G = 2x I_{GT}, t_r \le 100 \text{ns}$	50	A/µs
		f = 120 Hz, T _j = 125 °C		
T _j	Operating Temperature		(-40 +125)	°C
T _{stg}	Storage Temperature		(-40 +150)	°C
T _{sld}	Soldering Temperature	10s max	260	°C

SYMBOL	PARAMETER		Unit				
OTWIDOL		В	D	М	S	Ν	
V_{DRM}/V_{RRM}	Repetitive Peak Off State Voltage	200	400	600	700	800	V

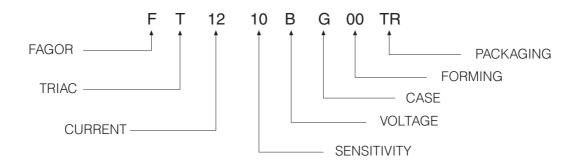


Electrical Characteristics at Tamb = 25 °C

SYMBOL	PARAMETER	CONDITIONS Quadrant			SENSITIVITY			Unit	
					10	13	18	17	
I _{GT} ⁽¹⁾	Gate Trigger Current	$V_D = 12 V_{DC}, R_L = 33\Omega, T_j = 25 ^{\circ}C$	Q1÷Q3	MAX	25	50	25	50	mA
			Q4	MAX	25	75	50	100	
V _{GT}	Gate Trigger Voltage	$V_D = 12 V_{DC}, R_L = 33\Omega, T_j = 25 ^{\circ}C$	Q1÷Q4	MAX		1.	3		V
V _{GD}	Gate Non Trigger Voltage	$V_D = V_{DRM}, R_L = 3.3 \text{ K}\Omega, T_j = 125 °C$	Q1÷Q4	MIN		0.	2		V
I _H ⁽²⁾	Holding Current	$I_T = 100 \text{ mA,Gate open}, T_j = 25 ^{\circ}\text{C}$		MAX	25	50	25	50	mA
IL	Latching Current	$I_G = 1.2 I_{GT}, T_j = 25 ^{\circ}\text{C}$	Q1, Q3, Q4	MAX	40	70	40	50	mA
			Q2	MAX	60	80	80	100	
dV/dt (2)	Critical Rate of Voltage Rise	$V_D = 0.67 \times V_{DRM}$, Gate open		MIN	400	1000	700	400	V/µs
		T _j = 125 °C							
(dV/dt)c ⁽²⁾	Critical Rate of Commutating off-state voltage	(dl/dt)c = 5.3 A/ms $T_j = 125$ °C		MIN	3	8	5	10	V/µs
V _{TM} ⁽²⁾	On-state Voltage	$I_T = 17 \text{ Amp, tp} = 380 \mu\text{s}, T_j = 25 ^{\circ}\text{C}$		MAX		1.5	55		V
V _{t (o)} (2)	Threshold Voltage	T _j = 125 °C		MAX		0.8	30		V
r _d ⁽²⁾	Dynamic resistance	T _j = 125 °C		MAX		7	0		mΩ
I _{DRM} /I _{RRM}	Off-State Leakage Current	$V_D = V_{DRM}$, $T_j = 125 ^{\circ}C$		MAX		1			mA
		$V_R = V_{RRM},$ $T_j = 25 ^{\circ}C$		MAX		5	5		μΑ
R _{th(j-c)}	Thermal Resistance Junction-Case	for AC 360° conduction angle				1.	4		°C/W
R _{th(j-a)}	Thermal Resistance Junction-Ambient	$s = 1 cm^2$				4	5		°C/W

⁽¹⁾ Minimum I_{GT} is guaranted at 5% of I_{GT} max.

Part Number Information



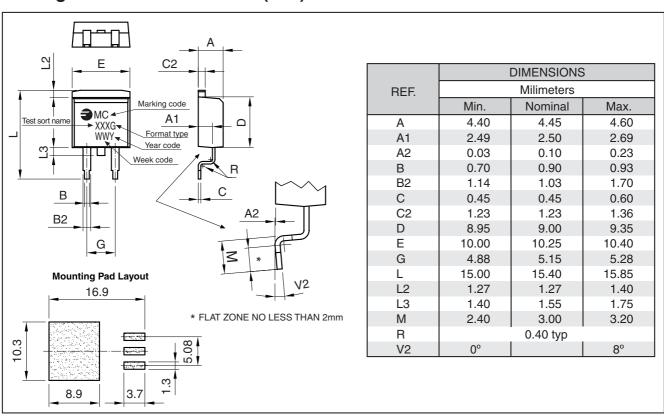
⁽²⁾ For either polarity of electrode MT2 voltage with reference to electrode MT1.



Ordering information

PREFERRED P/N	PACKAGE CODE	DELIVERY MODE	BASE QUANTITY	UNIT WEIGHT (g)
FT1217MG 00TR	T1217MG 00TR TR 13" diameter tape and reel 800		800	1.50

Package Outline Dimensions: (mm) TO-263AB / D2PAK





Ratings and Characteristics (Ta 25 °C unless otherwise noted)

Fig. 1: Maximum power dissipation versus RMS on-state current (full cycle)

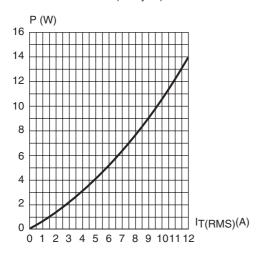


Fig. 3: Relative variation of thermal impedance versus pulse duration.

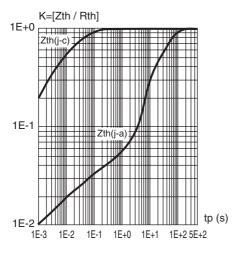


Fig. 5: Surge peak on-state current versus number of cycles

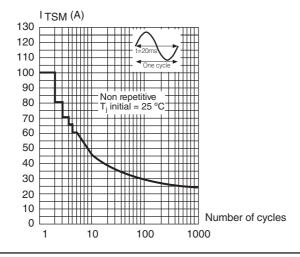


Fig. 2: RMS on-state current versus case temperature (full cycle).

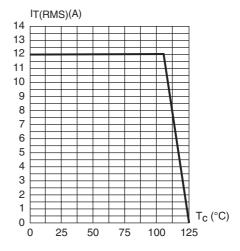


Fig. 4: On-state characteristics (maximum values)

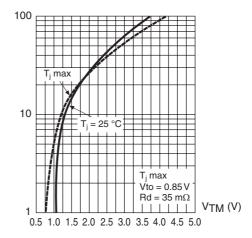
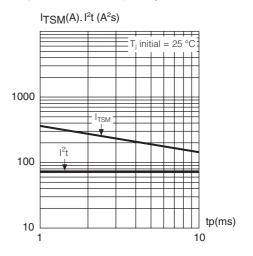


Fig. 6: Non repetitive surge peak on-state current for a sinusoidal pulse with width: tp < 10 ms, and corresponding value of I²t.





Ratings and Characteristics (Ta 25 °C unless otherwise noted)

Fig. 7: Relative variation of gate trigger current, holding current and latching versus junction temperature (typical values)

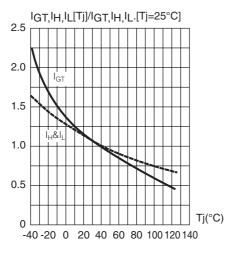


Fig. 9: Relative variation of critical rate of decrease of main current versus

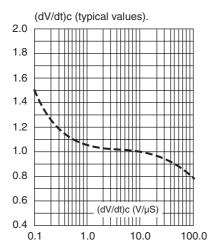


Fig. 8: Relative variation of critical rate of decrease of main current versus junction temperature

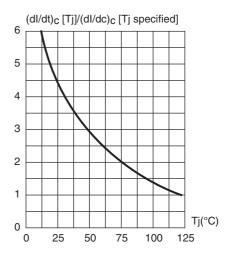
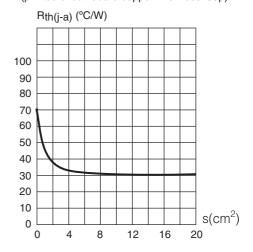


Fig. 10: D2PAK thermal resistance junction to ambient versus copper surface under tab (printed circuit board copper thickness: 35µ)





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